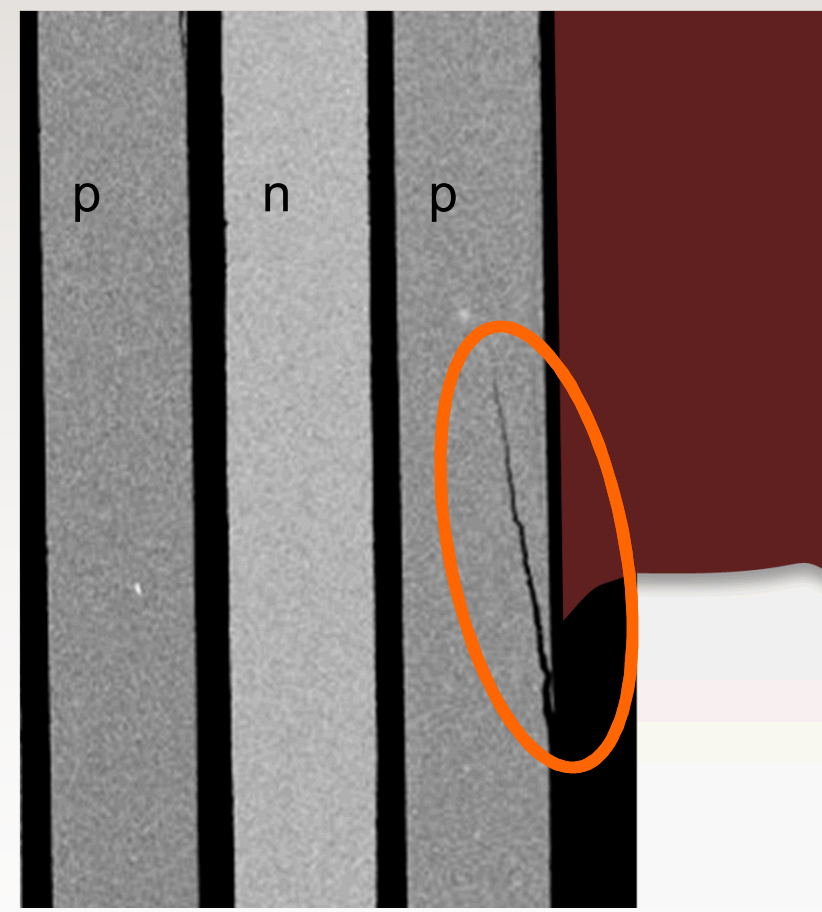
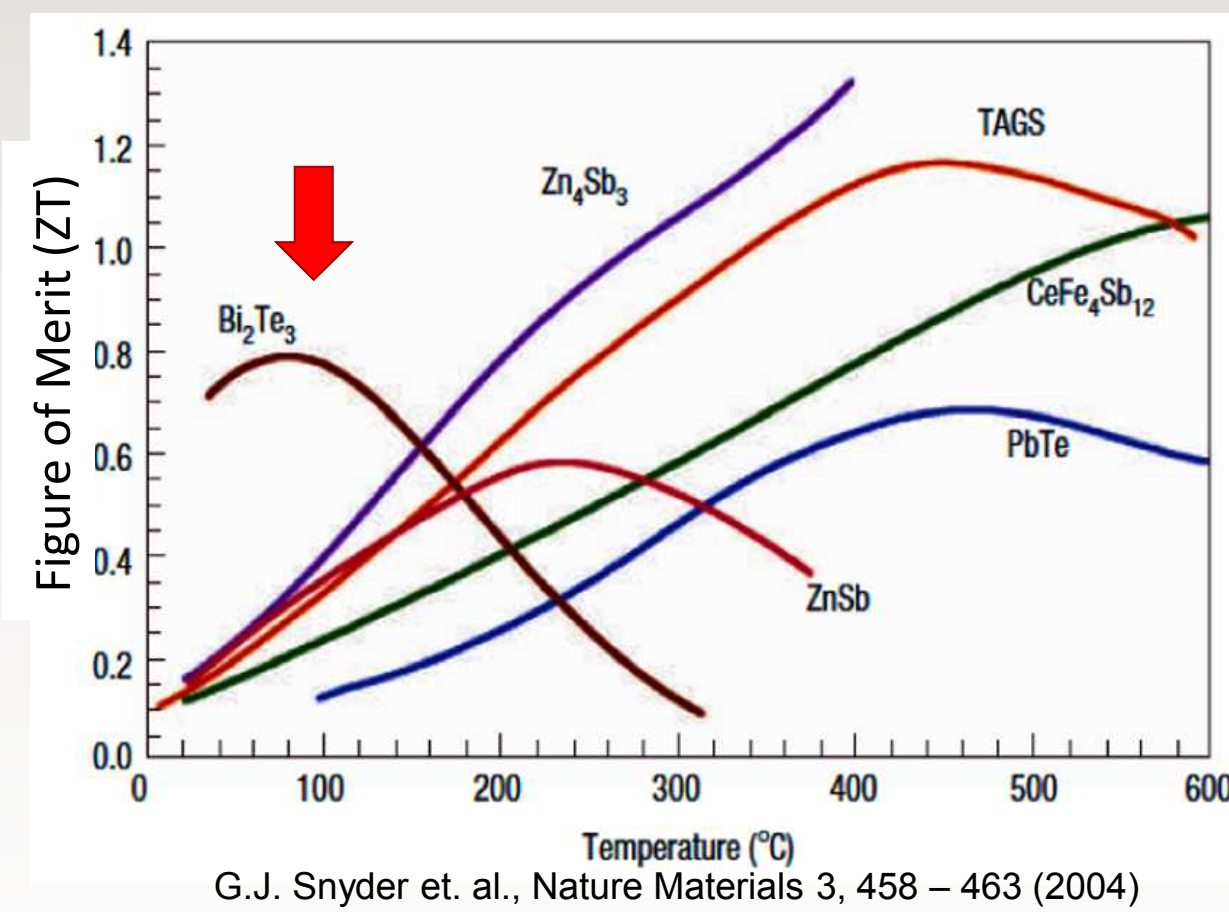
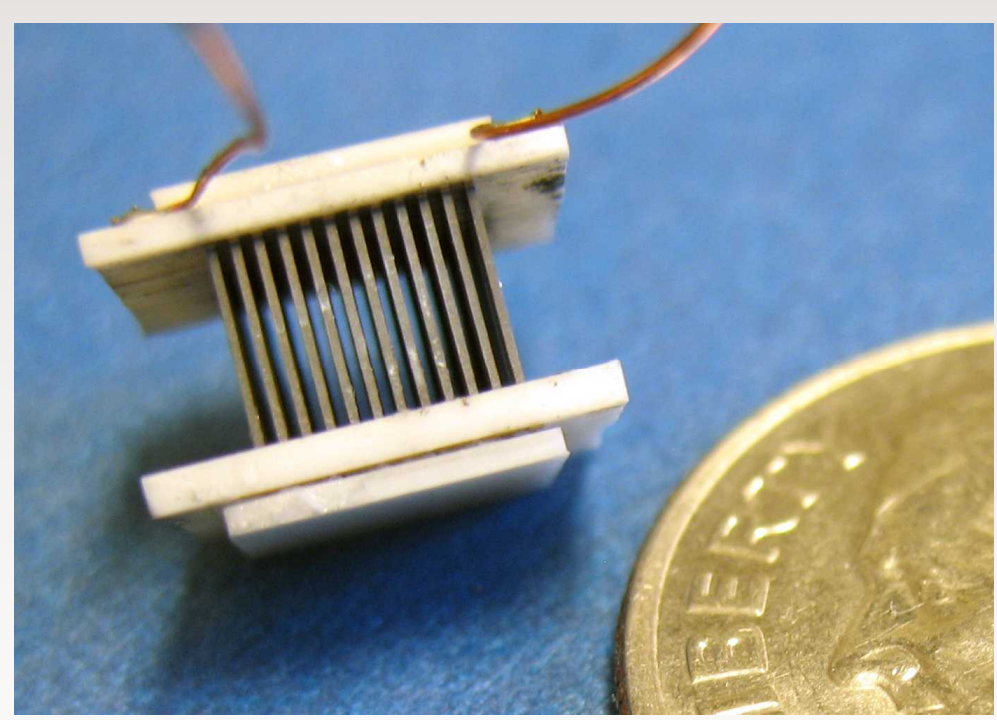


# Effects of Thermal Aging and Manufacture Induced Stress on Structure Integrity and Performance of TE Module

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## Mechanical Reliability of TE Module

- Bi<sub>2</sub>Te<sub>3</sub>-based TE module is good for low temperature applications
- The thermopiles may be susceptible to shock/vibration failure at locations of high residual stresses
- P-type: (Bi<sub>0.25</sub>Sb<sub>0.75</sub>)<sub>2</sub>Te<sub>3</sub>, N-type: Bi<sub>2</sub>(Te, Se)<sub>3</sub>



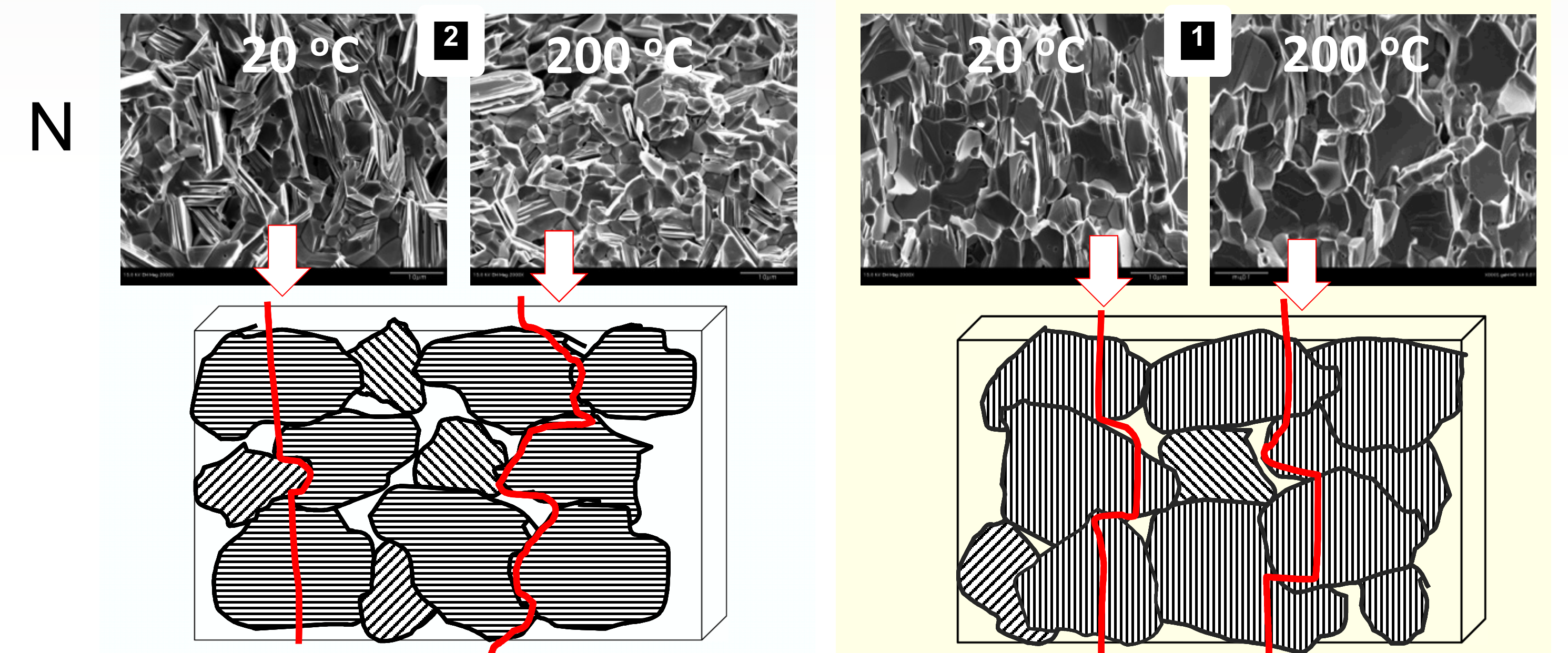
## Experimental Results (continued)

- Modulus ( $E$ ) and Strength ( $\sigma_{max}$ )

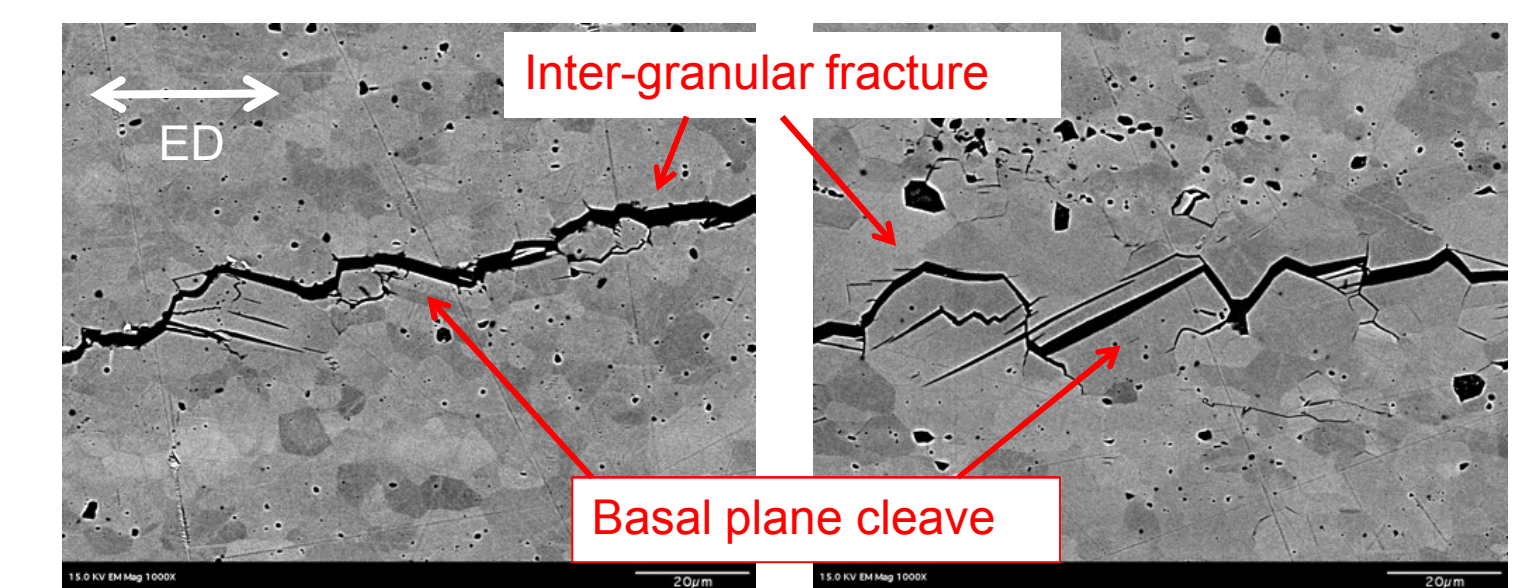
Specimen	$T = 20^\circ C$		$T = 200^\circ C$	
	$E$ (GPa)	$\sigma_{max}$ (GPa)	$E$ (GPa)	$\sigma_{max}$ (GPa)
N 1	34.9	60.0	32.0	59.7
N 2	38.5	88.6	26.8	67.3
P 1	24.8	44.5	23.7	48.1
P 2	35.8	86.4	25.9	70.5

## Failure Mechanism

- Group 1 samples, brittle basal cleavage mixed-in with inter-granular fracture, along the ED direction
- Group 2, trans-granular fracture, perpendicular to the ED direction; changes to inter-granular at 200 °C

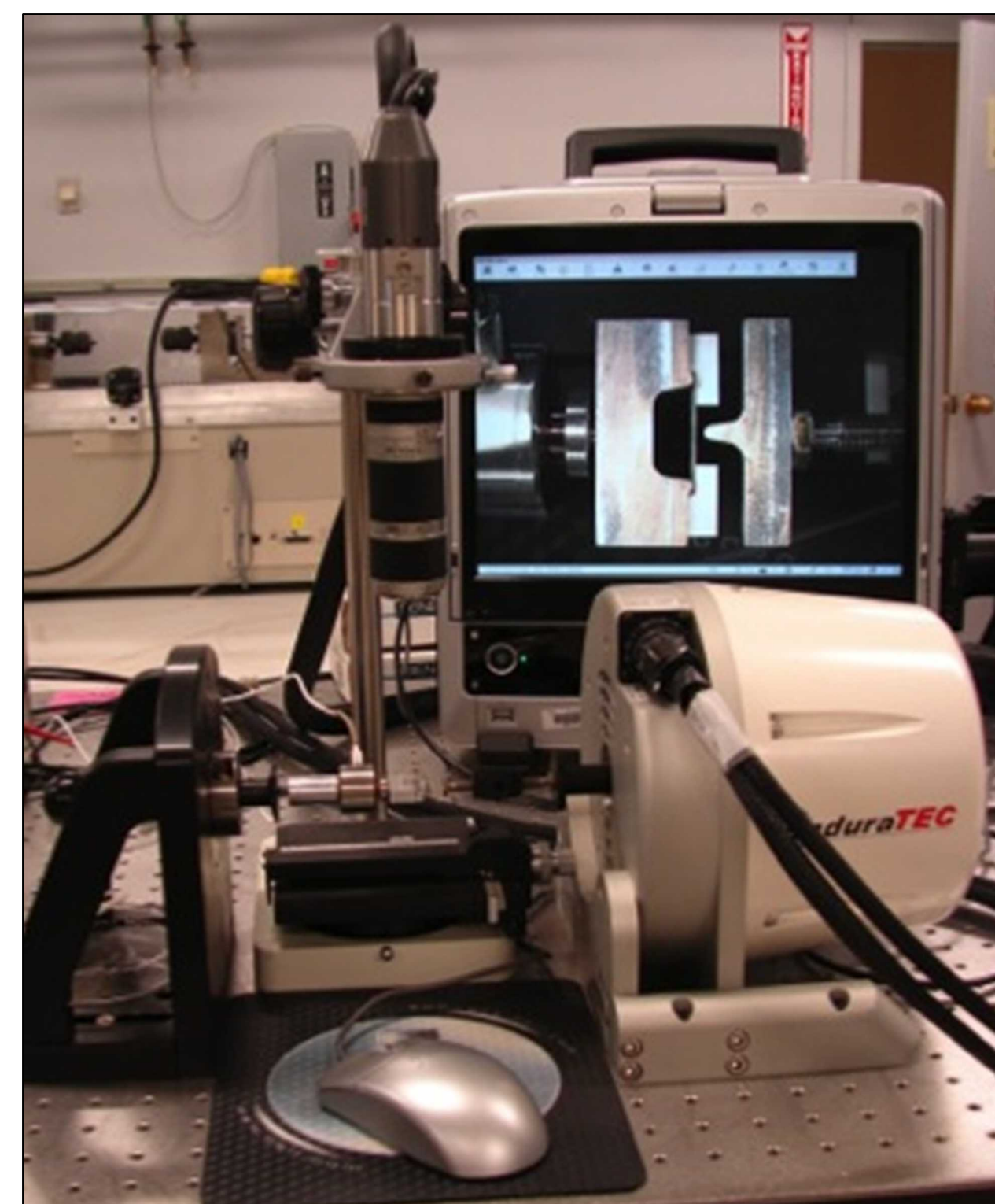
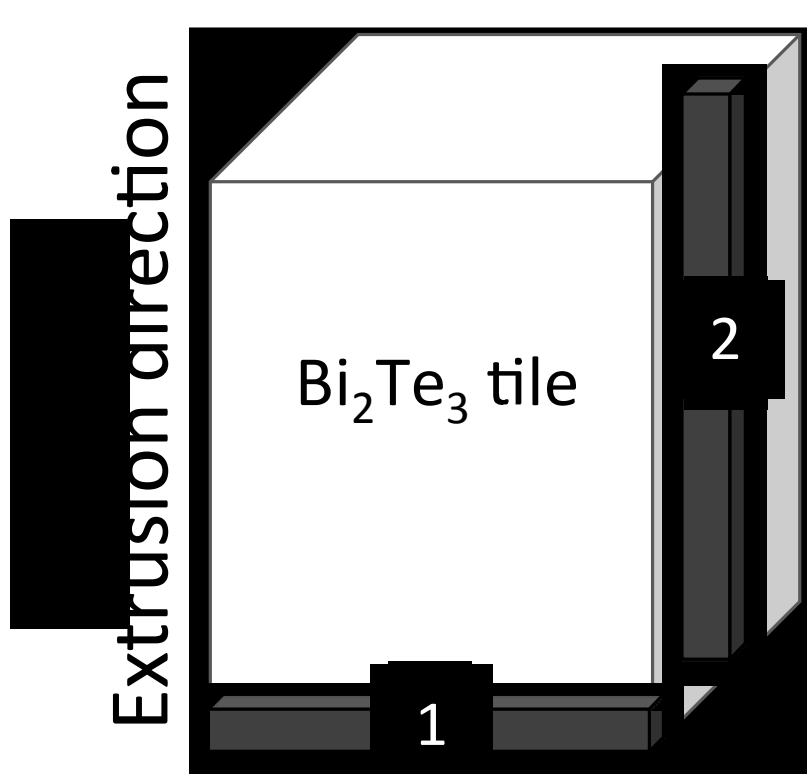


- Group 1 sample failure mechanisms are observed in finished TE modules



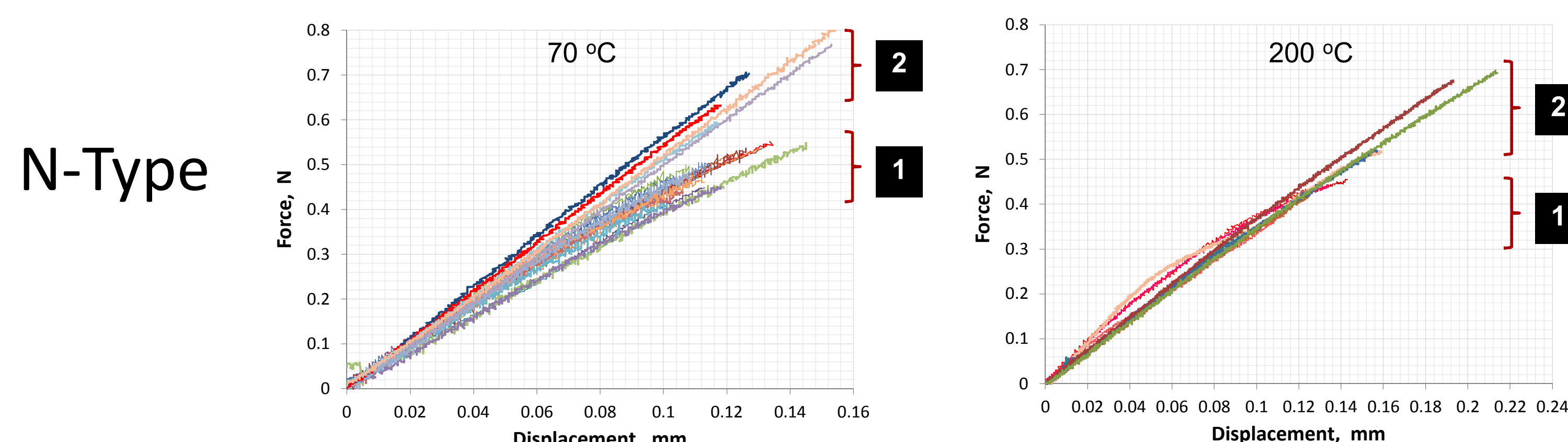
## Mechanical Properties of Fine-Sized Bi<sub>2</sub>Te<sub>3</sub>

- 3-point-bending test for elastic modulus and strength
- Testing at two temperatures, 20 and 200 °C
- P and N samples cut from the bulk rods in the axial (extrusion) and lateral directions
- Specimen dimension: 0.55W x 0.55H x 14L (span) mm



## Experimental Results

- Load – displacement curves



- P-Type has the similar trend

## Summary

- Mechanical properties of Bi<sub>2</sub>Te<sub>3</sub>-based alloys are dependent on crystal orientation and temperature
- The materials are brittle and susceptible to manufacture-induced stress cracking
- Optimization to minimize the residual stresses is necessary to mitigate the vulnerability of mechanical failure
- The measured mechanical properties are currently being used in computer simulations of fabrication processes and operational environments

